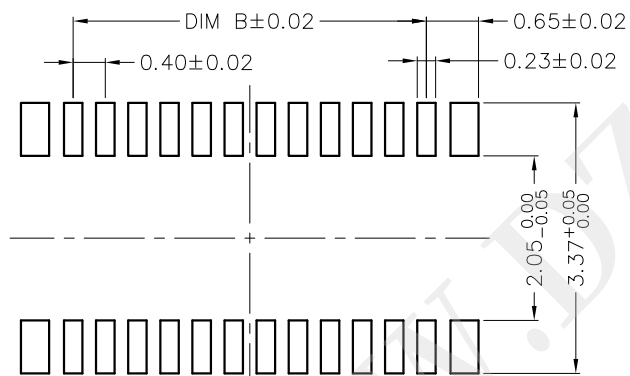
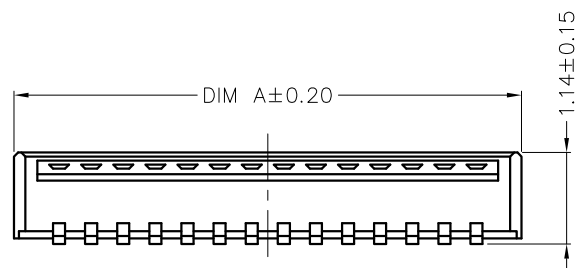
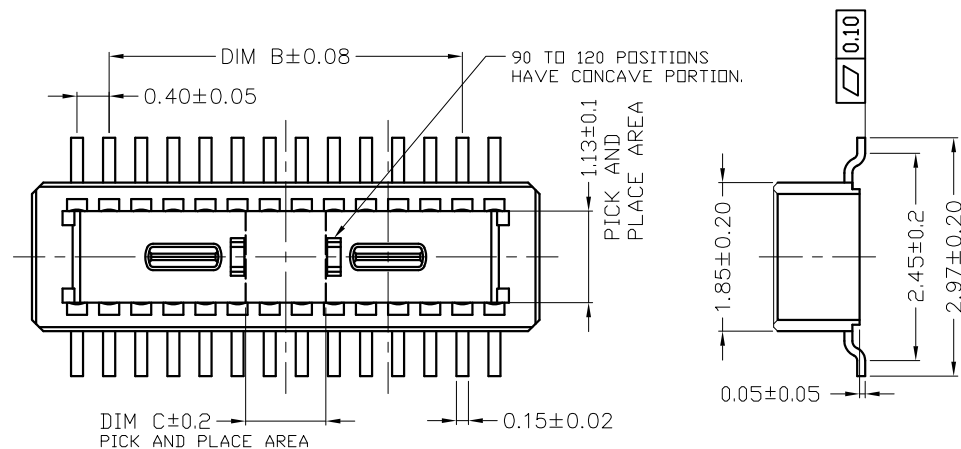




RECOMMENDED PCB LAYOUT

PIN NO.	DIM A	DIM B	DIM C
10	3.52	1.60	1.00
20	5.52	3.60	1.00
24	6.32	4.40	1.20
30	7.52	5.60	1.50
34	8.32	6.40	1.50
40	9.52	7.60	3.20
50	11.52	9.60	3.20
60	13.52	11.60	3.20
70	15.52	13.60	3.20
80	17.52	15.60	3.20
90	19.52	17.60	3.20
100	21.52	19.60	3.20
120	25.52	23.60	3.20

SPECIFICATIONS:

- 1.VOLTAGE/CURRENT RATING: 30V/AC, DC,0.3A;
- 2.WITHSTANDING VOLTAGE: 100V AC/ONE MINUTE;
- 3.INSULATION RESISTANCE: 50M Ω MIN/100V DC.;
- 4.CONTACT RESISTANCE: 90m Ω MAX./1mA,20mV AC,1KHz;
- 5.DURABILITY: 30 CYCLES;
- 6.OPERATING TEMPERATURE RANGE: -35°C TO 85°C .

MATERIAL:

- 1.INSULATOR: LCP UL 94V-0 BLACK;
- 2.TERMINAL: PHOSPHOR BRONZE;

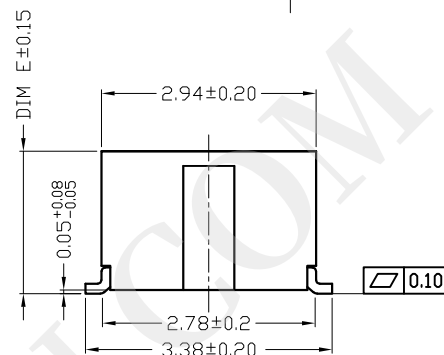
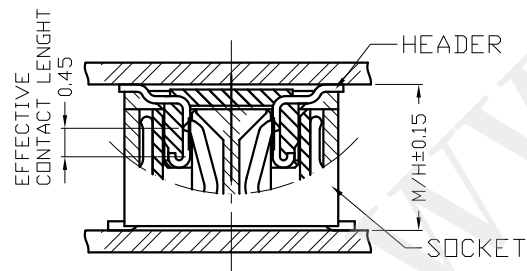
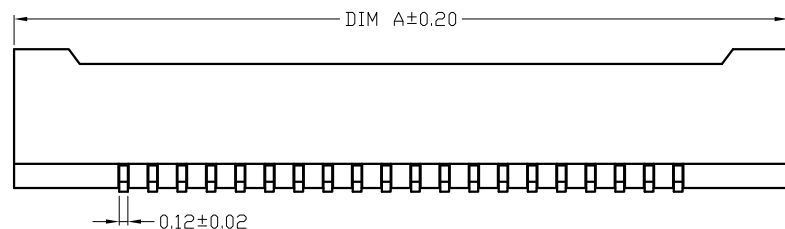
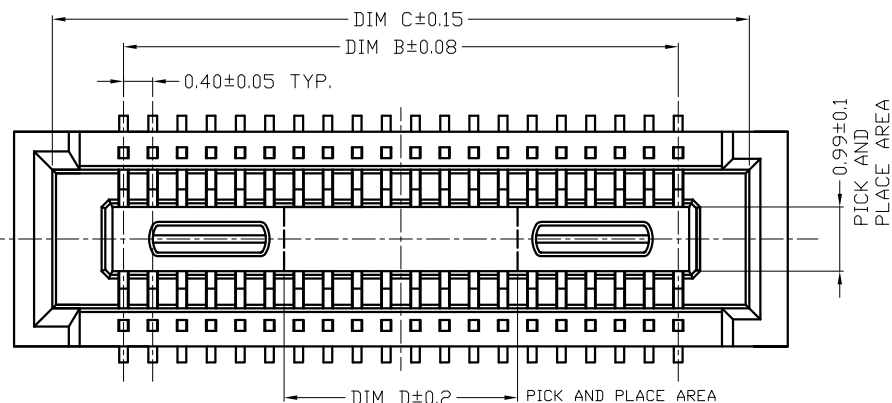
PLATING:

- 1.TERMINAL: CONTACT AREA: GOLD 0.05 μm "MIN.
SMT LEAD: GOLD 0.025 μm " MIN.
UNDERPLATING: NICKEL 1 μm " MIN.



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TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X." $\pm 2^{\circ}$ X.X" $\pm 0.5^{\circ}$	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 0.4PH 单槽BTB 公
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC20M-BTB2XN-114
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-2401251701
			SHEET NO. 1 OF 1



PIN NO.	DIM A	DIM B	DIM C	DIM D
10	4.60	1.60	3.55	1.00
20	6.60	3.60	5.55	1.00
24	7.40	4.40	6.35	1.20
30	8.60	5.60	7.55	1.50
34	9.40	6.40	8.35	1.50
40	10.60	7.60	9.55	3.20
50	12.60	9.60	11.55	3.20
60	14.60	11.60	13.55	3.20
70	16.60	13.60	15.55	3.20
80	18.60	15.60	17.55	3.20
90	20.60	17.60	19.55	3.20
100	22.60	19.60	21.55	3.20
120	26.60	23.60	25.55	3.20

M/H	2.00	2.50	3.00	3.50	4.00
DIM E	1.95	2.40	2.90	3.40	3.90

SPECIFICATIONS:

- 1.VOLTAGE/CURRENT RATING: 30V/AC, DC,0.3A;
- 2.WITHSTANDING VOLTAGE: 100V AC/ONE MINUTE;
- 3.INSULATION RESISTANCE: 50M Ω MIN/100V DC;
- 4.CONTACT RESISTANCE: 90m Ω MAX./1mA,20mV AC,1KHz;
- 5.DURABILITY: 30 CYCLES;
- 6.OPERATING TEMPERATURE RANGE: -35° C TO 85° C.

MATERIAL:

- 1.INSULATOR: LCP UL 94V-0 BLACK;
- 2.TERMINAL: PHOSPHOR BRONZE;

PLATING:

- 1.TERMINAL: CONTACT AREA: GOLD 0.05 μ m"MIN.
SMT LEAD: GOLD 0.025 μ m" MIN.
UNDERPLATING: NICKEL 1 μ m" MIN.



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5" UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 0.4PH 单槽BTB 母	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HVC20F-BTB2XN-XXX
	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO:	HVC-2401251701
			SHEET NO.	1 OF 1

RECOMMENDED PCB LAYOUT